Specification of Thermoelectric Module

TEFC1-02307P

Description

The 23 couples, 3.8mm× 5.04/6.04mm size porch type module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 74 ºC, designed for superior cooling and heating up to 100/200 ºC applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (ºC)	27	50	Hot side temperature at environment: dry air, N_2
DT_{max} (ºC)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U_{max} (Voltage)	3.03	3.26	Voltage applied to the module at DT_{max}
I_{max} (Amps)	0.7	0.7	DC current through the modules at DT_{max}
Q_{Cmax} (Watts)	1.36	1.48	Cooling capacity at cold side of the module under DT=0 ºC
AC resistance (Ohms)	3.27	3.47	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters
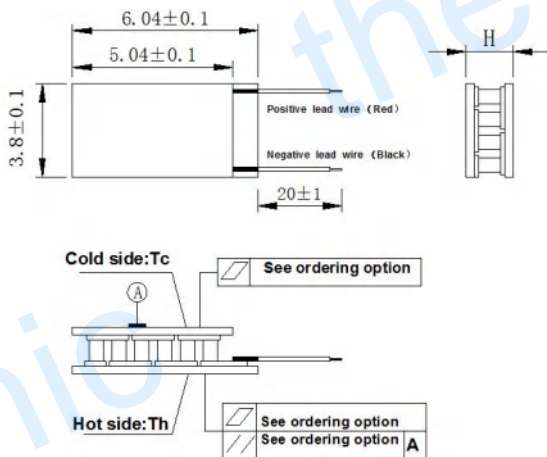
Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138ºC)

2. T200: CuAgSn (Tmelt = 217°C)

3. T240: SbSn (Tmelt = 240°C)

C. Ceramics:

1. Alumina (Al$_2$O$_3$, white 96%)

2. Aluminum Nitride (AlN)

B. Sealant:

1. NS: No sealing (Standard)

2. SS: Silicone sealant

3. EPS: Epoxy sealant
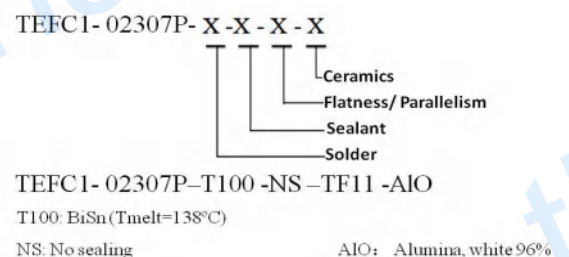
D. Ceramics Surface Options:

1. Blank ceramics (not metalized)

2. Metalized

Ordering Option

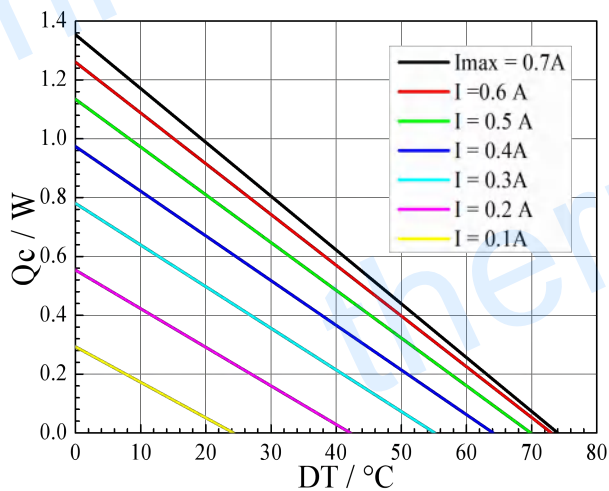| Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:1.8 ± 0.1	0: 0.03/0.03	20±1/Specify
TF	1:1.8 ± 0.03	1: 0.015/0.015	20±1/Specify
Eg. TF11: Thickness 1.8 ± 0.03 (mm) and Flatness 0.015/0.015 (mm)			

Naming for the Module

TEFC1- 02307P- X -X - X - X

                Ceramics
                Flatness/ Parallelism
                Sealant
                Solder

TEFC1- 02307P–T100 -NS –TF11 -AlO

T100: BiSn (Tmelt=138ºC)

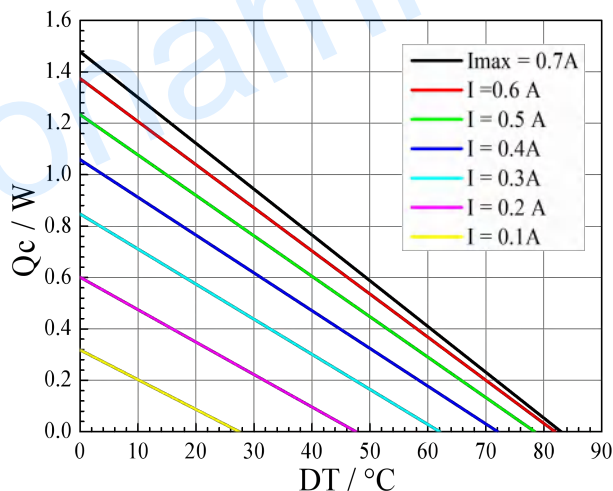NS: No sealing   AlO: Alumina, white 96%
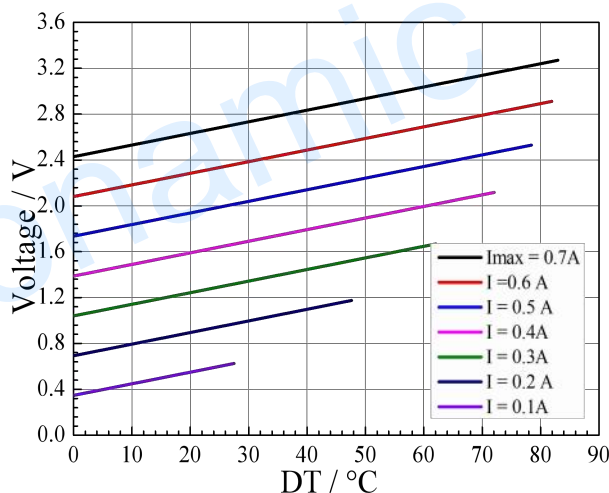
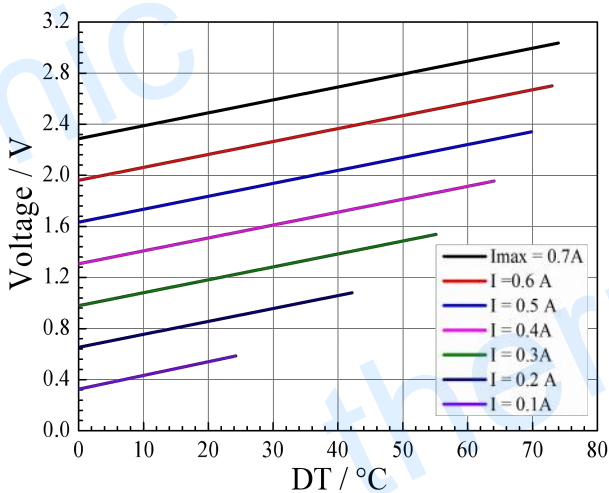# Specification of Thermoelectric Module

TEFC1-02307P

Performance Curves at Th=27 ºC

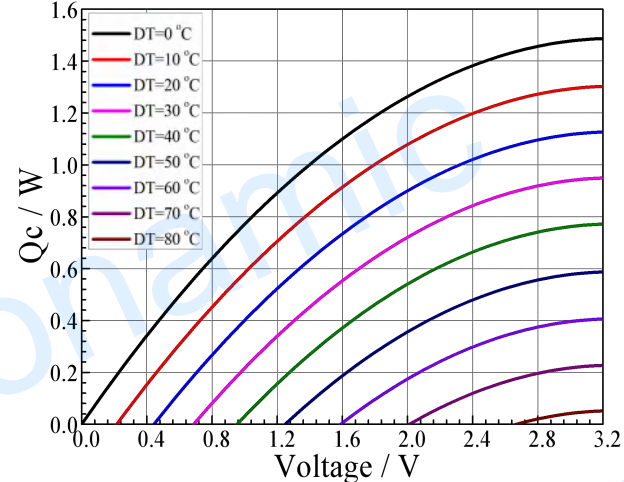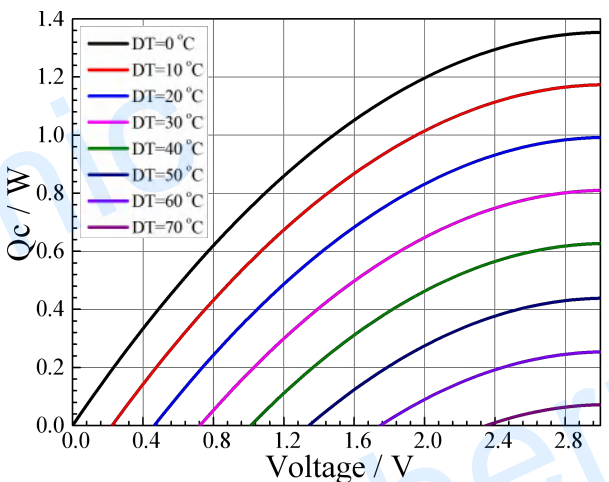### Performance Curves at Th=50 ºC

Standard Performance Graph Qc= f(DT)

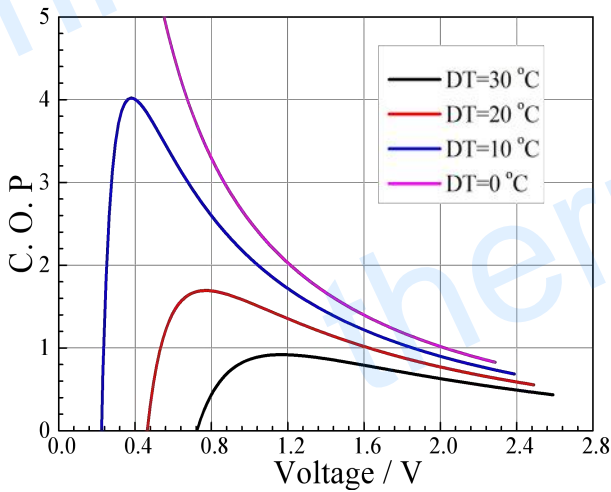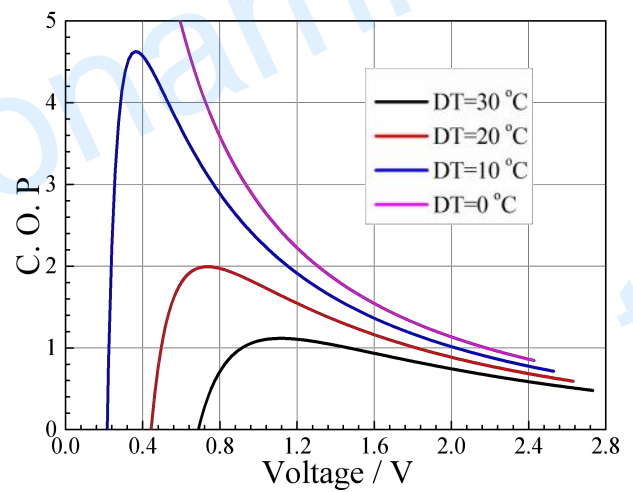Standard Performance Graph V= f(DT)

Standard Performance Graph Qc= f(V)

Specification of Thermoelectric Module
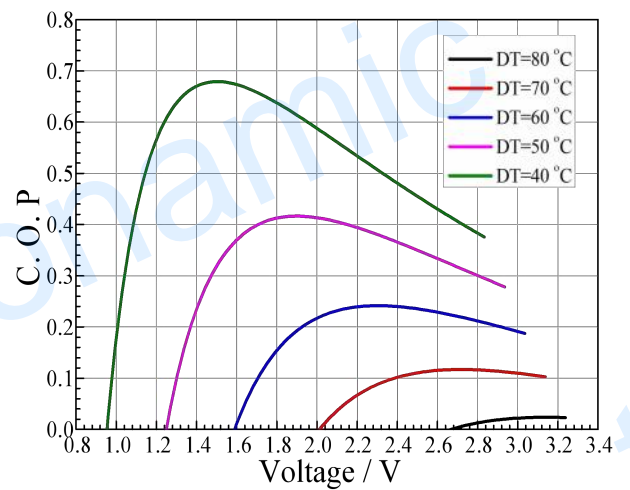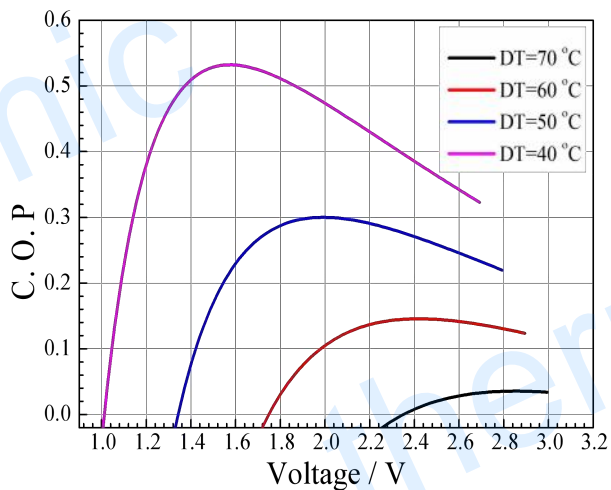
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Performance Curves at Th=27 ºC

Performance Curves at Th=50 ºC

Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 ˚C

Standard Performance Graph COP = f(V) of DT ranged from 40 to 70/80 ˚C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Caution

● Attach the cold side of module to the object to be cooled

● Attach the hot side of module to a heat radiator for heat dissipating

● Operation below I_{max} or V_{max}

● Work under DC

Note: All specifications subject to change without notice.